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(54) **METHOD AND SYSTEM FOR TREATING EMISSIONS USING A TRANSIENT PULSED PLASMA**

(57) A method and system to treat emissions (e.g., smoke, particulate, odor, grease) employs a nanosecond high voltage pulse generator, a transient pulsed plasma reactor, and a DC voltage source that supplies a DC bias voltage, preferably a negative DC bias voltage to a conductor of the transient pulsed plasma reactor. The system is used in a scheme that substantially reduces at least

particulate matter in emissions streams, for example emissions streams produced during cooking, for instance in commercial charbroiling processes (e.g., cooking of hamburger meat), or from operation of internal combustion engines. Both a reduction in the size distribution and total particulate mass is achieved using the method and system described herein.

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Description

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TECHNICAL FIELD

[0002] This description relates to systems and methods that employ high voltage, high power nanosecond pulses in treating emission, for example emissions from cooking, or from combustion engines (e.g., diesel, natural gas, gasoline engines).

BACKGROUND

[0003] Smoke emissions from chain-driven (*i.e.*, conveyor-belt) charbroilers has been regulated by the air quality management district (SC-AQMD) in southern California since 1997 (see RULE 1138). This "smoke" consists of oil particles (particulate matter) typically around 150nm in diameter. This problem has been "solved" using high temperature catalysts that cost \$1500-\$2000, are stable for more than 10 years, and are nearly maintenance-free. These catalyst-based systems make use of the high temperatures within a few inches of the cooking surface. However, these relatively large chain-driven charbroilers are only found in large fast food restaurants and comprise a relatively small fraction of total restaurant smoke emissions.

[0004] Open-underfire broilers (the kind most people are familiar with) are found in thousands of restaurants in the southern California area alone. These emissions are currently not regulated but account for 85% of all restaurant emissions in the South Coast region of California. Typical mass flow rates for these charbroilers are around 10 lbs/day or volumetric flow rates of 1600 ft³/min and higher. This corresponds to approximately 5 grams of particulate matter (PM) per hamburger. The same high temperature catalysts used for the chain-driven broilers are not applicable here, because the exhaust is cold by the time it reaches the hood approximately 1m away.

SUMMARY

[0005] The present disclosure is directed toward a system and method to remove and/or reduce smoke, particulate, odor, and/or grease from emissions streams, for example emission streams resulting from commercial or even residential cooking, for instance commercial charbroiling processes, or for example from internal combustion engines (e.g., diesel, natural gas, gasoline engines).

This is achieved by means of treating the emissions stream as it flows through an exhaust system and into a Transient Plasma Emission Remediation (TPER) Reactor, where it is treated with a non-equilibrated transient plasma that is generated by high voltage electrical pulses, each with a duration of nanoseconds, and to which a bias voltage is applied (e.g., negative DC bias voltage, positive DC bias voltage, sinusoidal or AC bias voltage) preferably has a least a negative voltage component.

[0006] In particular, a method and system for treating emissions streams, for example emissions from cooking appliances (e.g., charbroilers, broilers, grills, stove, ovens and other kitchen or restaurant equipment), includes an exhaust pathway (e.g., vent, duct), a TPER reactor positioned to treat an exhaust stream vented via the exhaust pathway, a nanosecond high voltage pulse generator coupled to drive the transient pulsed plasma reactor, and a voltage source (e.g., DC voltage source, sinusoidal voltage source) to supplement the TPER reactor with a bias voltage. The system substantially reduces one or more of smoke, particulate matter, odor and/or grease in the emission stream, produced, for example, in cooking, for instance in commercial charbroiling processes (e.g., cooking / grilling of hamburger meat), or produced in operation of, for example, internal combustion engines (e.g., diesel, natural gas, gasoline engines). Both a reduction in the size distribution and total particulate mass is advantageously achieved using the methods and systems described herein. Reduction in or treatment of smoke, odor and/or grease may also result.

[0007] A voltage source (e.g., DC voltage source, sinusoidal voltage source) may be connected to apply a bias voltage (e.g., negative DC bias voltage, positive DC bias voltage, sinusoidal or AC bias voltage) via a center conductor of a TPER reactor. In this configuration, the high voltage nanosecond pulses are coupled onto the center conductor of the TPER reactor and are superimposed on top of the bias voltage, which preferably has a least a negative component (e.g., sinusoidal, or negative DC bias voltage). This may be done either to produce a static electric field that lowers the electric field. The bias voltage may also be used to produce a static electric field that behaves like an electrostatic precipitator (ESP) and serves to precipitate particulate matter out of the gas flow.

[0008] The foregoing summary does not encompass the claimed subject matter in its entirety, nor are the embodiments intended to be limiting. Rather, the embodiments are provided as mere examples.

BRIEF DESCRIPTION OF THE DRAWINGS

[0009] In the drawings, identical reference numbers identify similar elements or acts. The sizes and relative positions of elements in the drawings are not necessarily drawn to scale. For example, the shapes of various elements and angles are not drawn to scale, and some of these elements are arbitrarily enlarged and positioned to improve drawing legibility. Further, the particular shapes

of the elements as drawn, are not intended to convey any information regarding the actual shape of the particular elements, and have been solely selected for ease of recognition in the drawings.

Figure 1 is a schematic diagram showing a system to treat emissions, for example cooking emissions, according to at least one illustrated implementation, the system including a kitchen ventilation system including a charbroiler, hood, duct, and blower, and the system also including a Transient Plasma Emission Remediation (TPER) reactor installed in a flow path of the kitchen ventilation system, and a nanosecond pulse generator coupled to drive the TPER reactor.

Figure 2 is a circuit diagram showing a circuit suitable for inclusion in the a nanosecond pulse generator of Figure 1, according to at least one illustrated implementation, the illustrated circuit operable to generate the high voltage, nanosecond duration electrical

pulses to generate plasma in the TPER reactor. Figure 3 is a schematic diagram showing a system to treat emissions, for example cooking emissions, according to at least another illustrated implementation, the system including a kitchen ventilation system including a charbroiler, hood, duct, and blower, and the system also including a Transient Plasma Emission Remediation (TPER) reactor installed in a flow path of the kitchen ventilation system, and a DC bias voltage in addition to a nanosecond pulse generator coupled to drive the TPER reactor.

Figure 4 is a circuit diagram showing both a voltage supply that supplies a bias voltage (e.g., negative DC bias voltage, positive DC bias voltage, sinusoidal or AC bias voltage) and the high voltage nanosecond supply coupled to drive the TPER reactor of Figure 3. Figure 5 is a schematic diagram of an experimental setup used to test a TPER reactor and nanosecond pulse generator.

Figure 6A is a graph that shows plots of a set of particle number densities versus particle size measured (using an SMPS) with and without the plasma treatment for a flow conditions of 2.5m/s.

Figure 6B is a graph that shows plots of a set of particle number densities versus particle size measured (using an SMPS) with and without the plasma treatment for a flow conditions of 0.25m/s.

Figure 7A is a graph that shows plots of a relative particle mass measured versus particle size with and without the plasma treatment for a flow condition of 2.5m/s.

Figure 7B is a graph that shows plots of a relative particle mass versus particle size measured with and without the plasma treatment for a flow condition of 0.25m/s.

Figure 8 is a graph that shows an integrated particle numbers (i.e., total particle number) plotted as a function of pulse repetition rate.

Figure 9A is a graph that shows a set of plots of a set of particle number densities for various sized particles measured for various respective pulser input voltages.

Figure 9B is a graph that shows a plot of integrated peak areas (i.e., total particle mass) plotted as a function of pulser input voltage.

Figure 10A is an isometric view of a plasma-based reactor for treating restaurant particulate emissions remediation, according to at least one illustrated implementation.

Figure 10B is a photograph of a plasma discharge at the output port of the reactor system of Figure 10A.

Figure 11 is a graph showing plots of a particle size distributions produced using POA-4 oil in an aerosol particle generator, with spectra captured 30 minutes apart using a scanning mobility particle sizer (SMPS).

Figure 12A is a graph showing a plot of a particle size distribution obtained with PAO-4 under an applied DC voltage of 5kV, both with and without a 30kV nanosecond pulsed plasma (pulse repetition rate of 200Hz and electrically continuous power of 30W).

Figure 12B is a graph showing a plot of a particle size distribution obtained with PAO-4 under an applied DC voltage 10kV, both with and without a 30kV nanosecond pulsed plasma (pulse repetition rate of 200Hz and electrically continuous power of 30W).

Figure 13A is a graph showing a particle size distribution obtained with soybean oil under an applied DC voltage of 2.5kV, both with and without the nanosecond pulsed plasma running at a peak voltage of 30kV, pulse repetition rate of 200Hz, and continuous power of 30W.

Figure 13B is a graph showing a particle size distribution obtained with soybean oil under an applied DC voltage of 5kV, both with and without the nanosecond pulsed plasma running at a peak voltage of 30kV, pulse repetition rate of 200Hz, and continuous power of 30W.

DETAILED DESCRIPTION OF THE PREFERRED EMBODIMENTS

[0010] In the following description, certain specific details are set forth in order to provide a thorough understanding of various disclosed embodiments. However, one skilled in the relevant art will recognize that embodiments may be practiced without one or more of these specific details, or with other methods, components, materials, etc. In other instances, certain structures associated with food preparation devices such as ovens, skillets, and other similar devices, closed-loop controllers used to control cooking conditions, food preparation techniques, wired and wireless communications protocols, geolocation, and optimized route mapping algorithms have not been shown or described in detail to avoid unnecessarily obscuring descriptions of the embodiments.

In other instances, certain structures associated with conveyors and/or robots are have not been shown or described in detail to avoid unnecessarily obscuring descriptions of the embodiments.

[0011] Unless the context requires otherwise, throughout the specification and claims which follow, the word "comprise" and variations thereof, such as, "comprises" and "comprising" are to be construed in an open, inclusive sense, that is as "including, but not limited to."

[0012] Reference throughout this specification to "one embodiment" or "an embodiment" means that a particular feature, structure or characteristic described in connection with the embodiment is included in at least one embodiment. Thus, the appearances of the phrases "in one embodiment" or "in an embodiment" in various places throughout this specification are not necessarily all referring to the same embodiment. Furthermore, the particular features, structures, or characteristics may be combined in any suitable manner in one or more embodiments.

[0013] As used in this specification and the appended claims, the singular forms "a," "an," and "the" include plural referents unless the content clearly dictates otherwise. It should also be noted that the term "or" is generally employed in its sense including "and/or" unless the content clearly dictates otherwise.

[0014] The headings and Abstract of the Disclosure provided herein are for convenience only and do not interpret the scope or meaning of the embodiments.

[0015] Figure 1 shows a system 100 to treat emissions, for example cooking smoke emissions, using a transient pulsed plasma, according to one illustrated implementation.

[0016] The system 100 includes a Transient Plasma Emission Remediation (TPER) reactor 102 and a nanosecond pulse generator 104 coupled to drive that TPER reactor 102. The TPER reactor 102 is designed to connect to an exhaust system 106, for example in series with one or more ducts 108a, 108b, 108c (three shown, collectively 108) that are part of the exhaust system 106 that vents the emissions (e.g., smoke, particulate, odor, grease) 109 generated, for example, by a cooking appliance 110 (e.g., charbroiler) out of a building and into the atmosphere. The exhaust system 106 may include one or more hoods 112 positioned relatively above the cooking appliance 110 to capture the cooking emissions (e.g., smoke, particulate, odor, grease) 109 produced by a combustion processor, for instance the cooking process. The hood 112 can take a variety of forms. The hood 112 will typically comprise a stainless steel sheet metal enclosure with a relative large hood input vent at one end, and a relatively smaller hood output vent at another end. The exhaust system 106 may include one or more blowers (e.g., fans) 114 positioned to draw and, or push the cooking emissions (e.g., smoke, particulate, odor, grease) 109 through the duct(s) 108 from the hood 112 to an exhaust outlet vent 116. The hood 112 and the ducts 108 define a fluid flow path (represented by arrows) 113 to constrain and guide passage of the capture the

emissions (e.g., smoke, particulate, odor, grease) 109. While illustrated in the context of a kitchen and cooking, the apparatus, methods and techniques described herein may be employed to treat other streams of emissions generated in other contexts. For example, the apparatus, methods and techniques described herein may be employed to treat other streams of emissions generated from operation of internal combustion engines (e.g., diesel, natural gas, gasoline engines).

[0017] In one embodiment, the TPER reactor 102 is comprised of a stainless steel cylindrical reactor anode 102a with a coaxial electrode 102b. This coaxial TPER reactor 102 comprises a thin wire, between 0.001 inch and 1 inch in diameter that is centered inside of an electrically conductive tube with an inner diameter between 1 inch and 24 inches, where the inner diameter is determined by the maximum voltage of the nanosecond pulse generator 104 that is driving the plasma generating reactor 102. An impedance of TPER reactor 102 is matched with a source cable 126 in order to reduce voltage reflections. The TPER reactor 102 provides a corona discharge in a coaxial cell geometry.

[0018] Figure 1 also shows the resulting transient plasma (i.e., high electron energy, low-temperature plasma) 118, as well as the shape of a typical high voltage pulse 120 produced by the nanosecond pulse generator and supplied to the TPER reactor 102. The plasma 118 is generated inside the TPER reactor 102 by driving a high voltage, nanosecond duration electrical pulse 120 onto the center conductor 102a or conductors of the TPER reactor(s) 102. In some implementations, the nanosecond duration electrical pulse 120 may have a duration of approximately equal to or less than 100 ns and may have a magnitude of approximately equal to or greater than >1 kV. For instance, suitable values for the nanosecond duration electrical pulse 120 may be a duration in a range of 0.1 ns to 100 ns, inclusive, and a magnitude in a range of 1 kV to 100 kV, inclusive.

[0019] In another implementation, a 4-electrode geometry is utilized for the plasma generating reactor 102, where the diameter of the wire generating the plasma and the outer tube are sized similarly to the ones described for the single wire geometry.

[0020] The system 100 may take the form of a retro-fit system, for example sized and dimensioned or shaped to be installed as part of a previously installed exhaust system, for example an exhaust system that draws emissions (smoke, particulate, odor, grease) from a vicinity of a cooking appliance and venting such into the atmosphere, typically with one or more filters. The retro-fit system may allow for the removal of one or more filters, for example including a replacement section or piece of duct to replace a section in which filters are mounted, or to provide a bypass fluid path around pre-existing filters or pre-existing filter section. In some implementations, one or more TPER reactors 102 could be installed on a roof of a building, for example connected in series with existing exhaust ducts.

[0021] Figure 2 shows a circuit 200 that is operable to generate a high voltage pulse to drive a TPER reactor 102, for example the TPER reactor 102 illustrated in Figure 1. A series of inductively coupled switching stages 202a, 202b, 202c, 202d (only four shown, collectively 202) discharge capacitors C₁, C₂, C₃, C₄ in series to achieve voltage multiplication. Operating switches M₁, M₂, M₃, M₄ causes energy to flow from these capacitors C₁, C₂, C₃, C₄ to energize a drift step recovery diode D₉, which rapidly interrupts energy stored by a charge circuit inductor L₅ to produce a high power, high voltage electrical pulse, which is transmitted to the anode or anodes of the TPER reactor 102.

[0022] Figure 3 shows a system 300 to treat emissions, for example cooking emissions (e.g., smoke, particulate, odor, grease) using a transient pulsed plasma, according to another illustrated implementation. The system 300 is similar to the system 100 (Figure 1), and similar or even identical structures are identified in Figure 3 with the same reference numbers as employed in Figure 1. In the interest of conciseness, only significant differences are discussed below.

[0023] In the system 300, a DC voltage source 302 may also be connected to the TPER reactor 102, in addition to the high voltage nanosecond pulse generator (e.g., power supply) 104. In this implementation, the nanosecond duration pulses 120 are coupled onto the anode or anodes of the TPER reactor 102, which is biased to a set DC voltage via the DC voltage source 302. The voltage of the nanosecond duration pulses 120 adds to the DC voltage.

[0024] Figure 4 shows a portion of a system 400 to treat emissions, for example cooking emissions (e.g., smoke, particulate, odor, grease) using a transient pulsed plasma, according to one illustrated implementation. In this implementation, the nanosecond pulses 120 (Figs. 1 and 3) are capacitively coupled onto the anode or anodes 102a (Figs. 1 and 3) of the TPER reactor 102 through a DC coupling capacitor C₁. A low pass filter (illustrated enclosed in broken-line box) 402 is used to isolate the DC supply (e.g., DC voltage source 302) from the high voltage, nanosecond duration pulse generator 104.

[0025] In particular, the system shows one implementation of how a DC voltage source 302 and a high voltage, nanosecond duration pulse generator (e.g., power supply) 104 may be connected to a TPER reactor 102. Both the DC voltage source 302 and the high voltage, nanosecond duration pulse generator 104 are electrically coupled to the anode or anodes of the TPER reactor 102. The DC voltage source 302 is electrically isolated from the high voltage, nanosecond pulse generator 104 by a low pass filter, comprised of inductor L_i, resistor R₂, and capacitor C₂. The high voltage, nanosecond pulse generator 104 is electrically isolated from the DC voltage source 302 by a coupling capacitor C₁. A resistor R₁ provides a DC path to allow the DC voltage source 302 to fully charge the coupling capacitor C₁. The values of cou-

pling capacitor C₁, inductor L_i, and capacitor C₂ are determined by the desired or defined pulse parameters of the high voltage, nanosecond pulse generator 104. Capacitor C₁ and capacitor C₂ are chosen to provide low impedance to the nanosecond duration pulse; whereas, inductor L_i is chosen to appear as a high impedance. The value of resistor R₁ is chosen to be sufficiently large so as to avoid excessive heating when the high voltage nanosecond pulse generator 104 is running at maximum or rated power. Resistor R₂ is chosen to sufficiently damp the resonance of inductor L_i, coupling capacitor C₁, and capacitor C₂. Applicants have determined that while a positive DC bias voltage produces favorable results for treating at least one of smoke, particulate, odor, and/or grease, a negative DC bias voltage produces particularly surprisingly even more favorable results. Applicants also note that a sinusoidal or AC bias voltage may produce favorable results for at least one of smoke, particulate, odor, and/or grease. In some implementations, DC voltage source may supply a negative or a positive bias voltage. In some implementations, a sinusoidal or AC may supply a sinusoidal or AC bias voltage which may be applied, or one portion (e.g., negative voltage portion, positive voltage portion) may be applied to the conductor.

[0026] A proof-of-principle experiment of this method and system has been performed in which a TPER reactor based system was tested in a test kitchen facility. Two TPER reactors were installed in parallel to a kitchen ventilation system including a charbroiler, hood, duct, and blower. Only a fraction of the full flow was passed through the TPER reactors.

[0027] Figure 5 shows a system 500 used to perform the experiment referred to immediately above. The system 500 is similar to the system 100 (Figure 1), and similar or even identical structures are identified in Figure 5 with the same reference numbers as employed in Figure 1. In the interest of conciseness, only significant differences are discussed below.

[0028] In contrast to the system 100 (Figure 1), the system 500 includes a main duct 502 and a tap duct 504. The tap duct 504 is used to tap or exhaust a slip stream of the smoke exhaust 506 from the main duct 502 and treated the slip stream of the smoke exhaust 506 by a pair of TPER reactors 508. The TPER reactors 508 comprise two 3" diameter TPER reactors, each 3 feet in length, and arranged in parallel with one another. Each TPER reactor 508 was powered by a nanosecond pulse generator 104, in particular a TPS Model 20X nanosecond pulse generator. The system 500 includes a spectrometer 510. The treated smoke exhaust 512 returns to the main duct 502 after being subjected to the non-equilibrated transient plasma.

[0029] In particular, particle distributions were collected using a Scanning Mobility Particle Sizer (SMPS) spectrometer (TSI Model 3776) over the range from 14-650nm. Hamburgers (75% lean, 25% fat) were cooked for 4.5 minutes per side continuously for 3 hours during this study, as shown in Figure 3. 15 patties were

cooked at a time on a grill that was 25×30" in area. A total of 375 patties were cooked during this study. The cooking emissions (e.g., smoke) 109 collected by the hood 112 was then treated with the TPER reactors.

[0030] Figure 6A is a graph 600a that shows the particle number densities measured with and without the plasma treatment via the experimental system 500 (Figure 5) described above at a reactor flow condition of 2.5m/s. Figure 6B is a graph 600b that shows the particle number densities measured with and without the plasma treatment via the experimental system 500 (Figure 5) described above for a reactor flow condition of 0.25m/s. The integrated peak areas are indicated in Figures 6A and 6B. For these datasets, the original untreated particle distributions are peaked around 125-150nm diameter. With plasma treatment, a significant drop in the particle number was observed along with the emergence of a narrow distribution centered around 30-40nm. The integrated area of the dominant peak shows a factor of 1.7X reduction in PM number density (i.e., $4.62/2.71=1.7X$) at high flow rates (2.5m/s) and a 10-fold reduction in PM at low flow rates (0.25m/s).

[0031] Since smaller diameter nanoparticles have substantially lower mass than larger diameter nanoparticles, it may be more appropriate to plot the particle mass instead of number density. Figures 7A and 7B are graphs 700a, 700b, respectively, that show the "Relative Particle Mass" in arbitrary units obtained by multiplying the number densities in Figures 3 and 4, respectively, by the diameter cubed. The integrated peak areas are indicated in Figures 7A and 7B. Here, 2.4X and 55X-fold reductions in total PM mass were observed for flow rates of 2.5 and 0.25 m/s, respectively.

[0032] The particle distributions were also measured as a function of the pulse repetition rate. Figure 8 is a graph 800 that shows the integrated particle number plotted as a function of pulse repetition rate, which decreases linearly with increasing repetition rate. Here, the total particle number decreases linearly with increasing repetition rate. These results demonstrate the scalability of this approach for treating higher flow rates and larger systems at higher repetition rates.

[0033] Figure 9A is a graph 900a that shows the particle distributions as a function of voltage dependence. Figure 9B is a graph 900b that shows a plot of integrated peak areas (i.e., total particle mass) plotted as a function of pulser input voltage for the particle distributions of Figure 9A. Here, again, a monotonic decrease is observed in the integrated area of the PM peak distribution (i.e., total PM mass), with an overall reduction of 40X observed at a pulser input voltage of 400 VDC. These input voltages correspond to pulse energies of approximately 10, 20, 40, and 50mJ. These results demonstrate the scalability of this approach for treating higher flow rates and larger systems with higher pulse powers.

[0034] These measurements demonstrate the effectiveness of transient pulsed plasmas to provide substantial remediation of particulate matter (PM) produced by

commercial charbroiling processes (e.g., cooking of hamburger meat). The scalability of this approach for treating higher flow rates and larger systems is also demonstrated as a function of both pulse repetition rate and pulse energy.

[0035] This plasma-based approach provides a fundamentally different mechanism for breaking down oil-based particulate matter that cannot be achieved with conventional UV and/or ozone approaches, both of which are present in the plasma. Here, highly reactive chemical radical species, including atomic oxygen, are largely responsible for the effective breakdown of these oil aerosol particles.

[0036] One possible advantage of this plasma-based approach lies in the substantially improved flow through the system, which reduces the power requirements associated with the fan or blower. Typically, with filter-based approaches, 2-3 filters are configured in series, resulting in a considerable pressure drop which, in turn, requires high power blowers to be utilized in order to achieve the necessary flow rates for kitchen ventilation compliance. Since there is essential no pressure drop across the plasma-based reactor, significantly lower blower powers can be used to achieve the same flow rates, enabling the overall system (including the nanosecond pulse generator) to consume less power than current filter-based systems.

[0037] Other features of the disclosed embodiments will become apparent from the following detailed description, taken in conjunction with the accompanying drawings, which illustrate, by way of example, the principles of the disclosed embodiments.

[0038] Another proof-of-principle experiment of the method by which a DC bias is applied together with the nanosecond pulse is shown in Figures 10A, 10B, 11, 12A, 12B, 13A and 13B. Here, both polyaromatic olefin PAO-4 and soybean oil particulates created by an oil aerosol generator are treated. As illustrated by the data, a more than three-order-of-magnitude reduction in particulates (i.e., 99.9% remediation) can be achieved with the treatment system described herein. In these tests, the plasma discharge is produced in a 4" diameter cylindrical reactor (illustrated in Figures 10A and 10B) with a 5-10 nanosecond high voltage (30 kV) pulse generator together with applied DC bias voltages up to 20 kV. The distribution of nanoparticle sizes is centered around 225 nm in diameter, as measured using a scanning mobility particle sizer (SMPS) spectrometer and follows a log-normal distribution.

[0039] In this experiment, an oil aerosol generator from Aerosol Technologies International (ATI, Inc.) was employed, which creates an oil aerosol by forcing compressed air through a Laskin nozzle. The plasma-based flow reactor used comprises a 4 foot-long, 4 inch-diameter stainless steel cylindrical anode with a 25mil single-wire cathode arranged in a coaxial geometry, as illustrated in Figures 10A and 10B. This plasma-based flow system has electrical feedthroughs on either end of the re-

actor, one for supplying high DC voltages and the other for high voltage nanosecond pulses, as indicated in Figure 10A. AC and DC filters have been built into these feedthroughs in order to protect the nanosecond pulse generator from the high voltage DC bias and vice versa. The plasma is produced using a TPS Model 30X pulse generator operating at a peak voltage of 30kV, a pulse repetition rate of 200Hz, and a continuous power of 30W. Here, the generation of plasma is assisted by 20kV DC power supply capable of supplying up to 30W of continuous power. Baseline particle distributions (*i.e.*, histograms) were measured using a scanning mobility particle sizer (SMPS) without a plasma or DC bias and exhibit highly stable distributions, as show in Figure 11.

[0040] Figure 12A shows particle size distributions taken under an applied DC voltage of 5kV both with and without the nanosecond pulse generator running at a peak voltage of 30kV, pulse repetition rate of 200Hz, and continuous electrical power of 30W. A comparison of these two distributions shows a more than 12-fold reduction of total PM concentration (*i.e.*, 92% remediation). Here, the integrated areas are indicated in the plot corresponding to the total particle concentrations both with and without the transient pulsed plasma. Similarly, Figure 12B shows particle size distributions taken with an applied DC voltage of 10kV both with and without a nanosecond pulse generator, exhibiting a more than 1500-fold reduction in PM concentration (*i.e.*, 99.9% remediation). It should be noted that the particle distributions taken with 5kVDC and 10kVDC only, without the nanosecond pulse generator, are nearly identical to the untreated baseline data (*i.e.*, no remediation) plotted in Figure 11.

[0041] A separate set of measurements was taken using soybean oil rather than PAO-4. The soybean oil more closely resembles the oil-based nanoparticles that are generated by the charbroiling of hamburger meat and is often used as a surrogate grease generator following the UL 1046 standard method. However, it is also worth noting that these soybean oil grease aerosol particles are generated at room temperature and do not contain any carbonaceous particles, such as those produced in the combustion of natural gas. Figure 13A shows particle size distributions taken with an applied DC voltage of 2.5kV both with and without the nanosecond pulsed plasma. Figure 13B shows particle size distributions taken with an applied DC voltage of 5kV both with and without the nanosecond pulsed plasma. For a DC bias of 2.5kV, a 21-fold reduction in PM concentration (*i.e.*, 96% remediation) was observed. For a DC bias of 5kVDC, a more than 1260-fold reduction in PM concentration (*i.e.*, 99.9% remediation) was observed. Without being bound by theory, the improved remediation obtained with a DC bias of 5kV compared to that of 2.5kVDC can be attributed to the increased electric fields that are achieved when adding the 30kV peak pulse voltage. At higher DC biases, the plasma density is higher and fills a more substantial volume of the reactor. It should, again, be noted that the distributions observed with 2.5 and 5kVDC bias only (*i.e.*,

without the nanosecond pulse generator) are nearly identical to the untreated data (*i.e.*, no remediation).

[0042] Various embodiments of the devices and/or processes via the use of block diagrams, schematics, and examples have been set forth herein. Insofar as such block diagrams, schematics, and examples contain one or more functions and/or operations, it will be understood by those skilled in the art that each function and/or operation within such block diagrams, flowcharts, or examples can be implemented, individually and/or collectively, by a wide range of hardware, software, firmware, or virtually any combination thereof. In one implementation, the present subject matter may be implemented via Application Specific Integrated Circuits (ASICs). However, those skilled in the art will recognize that the embodiments disclosed herein, in whole or in part, can be equivalently implemented in standard integrated circuits, as one or more computer programs running on one or more computers (*e.g.*, as one or more programs running on one or more computer systems), as one or more programs running on one or more controllers (*e.g.*, microcontrollers) as one or more programs running on one or more processors (*e.g.*, microprocessors), as firmware, or as virtually any combination thereof, and that designing the circuitry and/or writing the code for the software and or firmware would be well within the skill of one of ordinary skill in the art in light of this disclosure.

[0043] When logic is implemented as software and stored in memory, one skilled in the art will appreciate that logic or information, can be stored on any nontransitory computer-readable medium for use by or in connection with any computer and/or processor related system or method. In the context of this document, a memory is a computer-readable medium that is an electronic, magnetic, optical, or other another physical device or means that contains or stores a computer and/or processor program. Logic and/or the information can be embodied in any computer-readable medium for use by or in connection with an instruction execution system, apparatus, or device, such as a computer-based system, processor-containing system, or other system that can fetch the instructions from the instruction execution system, apparatus, or device and execute the instructions associated with logic and/or information. In the context of this specification, a "computer-readable medium" can be any means that can store, communicate, propagate, or transport the program associated with logic and/or information for use by or in connection with the instruction execution system, apparatus, and/or device. The computer-readable medium can be, for example, but not limited to, an electronic, magnetic, optical, electromagnetic, infrared, or semiconductor system, apparatus, device, or propagation medium. More specific examples (a non-exhaustive list) of the computer-readable medium would include the following: an electrical connection having one or more wires, a portable computer diskette (magnetic, compact flash card, secure digital, or the like), a random access memory (RAM), a read-only memory (ROM), an

erasable programmable read-only memory (EPROM, EEPROM, or Flash memory), an optical fiber, and a portable compact disc read-only memory (CDROM). Note that the computer-readable medium, could even be paper or another suitable medium upon which the program associated with logic and/or information is printed, as the program can be electronically captured, via for instance optical scanning of the paper or other medium, then compiled, interpreted or otherwise processed in a suitable manner if necessary, and then stored in memory.

[0044] In addition, those skilled in the art will appreciate that certain mechanisms of taught herein are capable of being distributed as a program product in a variety of forms, and that an illustrative embodiment applies equally regardless of the particular type of nontransitory signal bearing media used to actually carry out the distribution. Examples of nontransitory signal bearing media include, but are not limited to, the following: recordable type media such as floppy disks, hard disk drives, CD ROMs, digital tape, and computer memory.

[0045] The various embodiments described above can be combined to provide further embodiments. U.S. patent application Serial No. 16/586,514; U.S. patent application Serial No. 16/508,069; U.S. patent application Serial No. 62/699,475; U.S. patent 8,115,343; International patent application No. PCT/US2019/014339; International patent application No. PCT/US2019/014273; U.S. patent 9,617,965, are each incorporated herein by reference, in their entirety.

[0046] From the foregoing it will be appreciated that, although specific embodiments have been described herein for purposes of illustration, various modifications may be made without deviating from the spirit and scope of the teachings. Accordingly, the claims are not limited by the disclosed embodiments.

Claims

1. A method to treat exhaust streams, the method comprising:

capturing an exhaust stream;
driving a transient plasma emission remediation (TPER) reactor with a high voltage pulse with a duration of nanoseconds to generate a non-equilibrated transient plasma in a portion of the TPER reactor through which the captured exhaust stream passes;
applying a negative bias voltage or a sinusoidal bias voltage by a voltage source to an energized conductor of the TPER reactor; and
passing the captured exhaust stream through the TPER reactor drive with the high voltage, nanosecond duration pulse and the applied negative bias voltage or sinusoidal bias voltage.

2. The method of claim 1 wherein the voltage source

is a DC voltage source and applying a negative bias voltage or a sinusoidal bias voltage by a voltage source to an energized conductor of the TPER reactor includes applying a negative DC bias to an energized conductor of the TPER reactor.

3. The method of claim 1 wherein the voltage source is a sinusoidal voltage source and applying a negative bias voltage or a sinusoidal bias voltage by a voltage source to an energized conductor of the TPER reactor includes applying a sinusoidal bias to an energized conductor of the TPER reactor.

4. The method of any of claims 2 or 3 wherein applying a negative bias voltage or a sinusoidal bias voltage by a voltage source to an energized conductor of the TPER reactor includes applying a negative bias voltage or a sinusoidal bias voltage that produces a static electric field that does not produce an electrical discharge.

5. The method of claim any of claims 2 or 3 wherein applying a negative bias voltage or a sinusoidal bias voltage by a voltage source to an energized conductor of the TPER reactor includes applying a negative bias voltage or a sinusoidal bias voltage that lowers a field needed to be generated by the high voltage, nanosecond duration pulse.

6. The method of any of claims 2 or 3 wherein applying a negative bias voltage or a sinusoidal bias voltage by a voltage source to an energized conductor of the TPER reactor includes applying a negative DC bias voltage that produces a static electric field that precipitates particulate matter out of the gas flow.

7. The method of any of claims 1 through 3, further comprising:
coupling the high voltage, nanosecond duration pulse onto a negative bias voltage or a sinusoidal bias voltage biased conductor of the TPER reactor through a coupling capacitor, and isolating the voltage source from a source of the high voltage, nanosecond duration pulse by a low pass filter.

8. The method of any of claims 1 through 3 wherein driving the TPER reactor with a high voltage pulse with a duration of nanoseconds includes applying an electric field of the high voltage, pulse with a nanosecond duration pulse on top of a static electric field produced by the negative bias voltage or the sinusoidal bias voltage.

9. The method of any of claims 1 through 3 wherein driving the TPER reactor with a high voltage pulse with a duration of nanoseconds includes applying a fast rising, high voltage pulse with a duration of nanoseconds to at least one electrode of the TPER

reactor.

10. The method of any of claims 1 through 3 wherein capturing an exhaust stream includes capturing the exhaust stream via a hood positioned over a cooking appliance. 5
11. The method of claim 10 wherein capturing the exhaust stream via a hood positioned over a cooking appliance includes capturing at least two of: smoke, particulate, grease and odor generated by charbroiling of meat by a charbroiler. 10
12. The method of any of claims 1 through 3 wherein capturing an exhaust stream includes capturing the exhaust stream from an internal combustion engine. 15
13. A system to treat exhaust streams, the system comprising: 20
at least one a transient plasma emission remediation (TPER) reactor, the at least one a TPER reactor including an electrically conductive tube that forms a first electrode and at least a second electrode positioned in an interior of the electrically conductive tube, the electrically conductive tube sized to be serially coupled in a flow path formed by one or more ducts; 25
at least one nanosecond pulse generator coupled to drive the at least one TPER reactor; and 30
a high voltage source electrically coupled to apply a negative bias voltage or a sinusoidal bias voltage to at least one conductor of the at least one TPER reactor. 35
14. The system of claim 13 wherein the voltage source is a DC voltage source and applies a negative DC bias to an energized conductor of the TPER reactor.
15. The system of any of claims 13 or 14, further comprising: 40
a coupling capacitor through which a high voltage, nanosecond duration pulse is coupled onto the at least one conductor to which the negative DC bias voltage is applied; and 45
a low pass filter that isolates the DC high voltage source from the at least one nanosecond pulse generator that generates high voltage, nanosecond duration, and wherein: 50
the at least one nanosecond pulse generator coupled to drive the at least one TPER reactor is operable to supply a fast rising, high voltage pulse with a duration of nanoseconds to produce a non-equilibrated transient plasma inside at least a portion of the at least one TPER reactor. 55

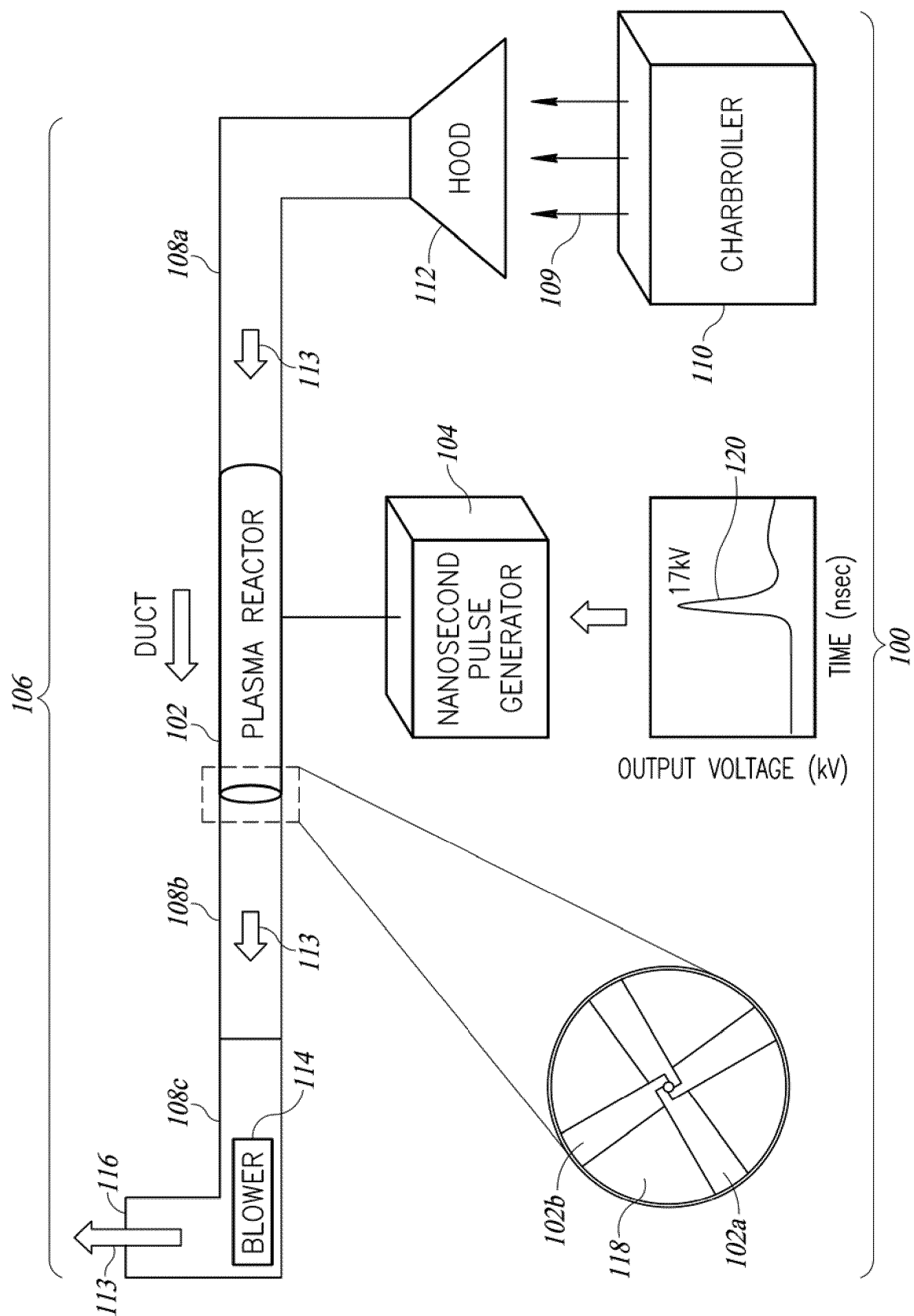


FIG. 1

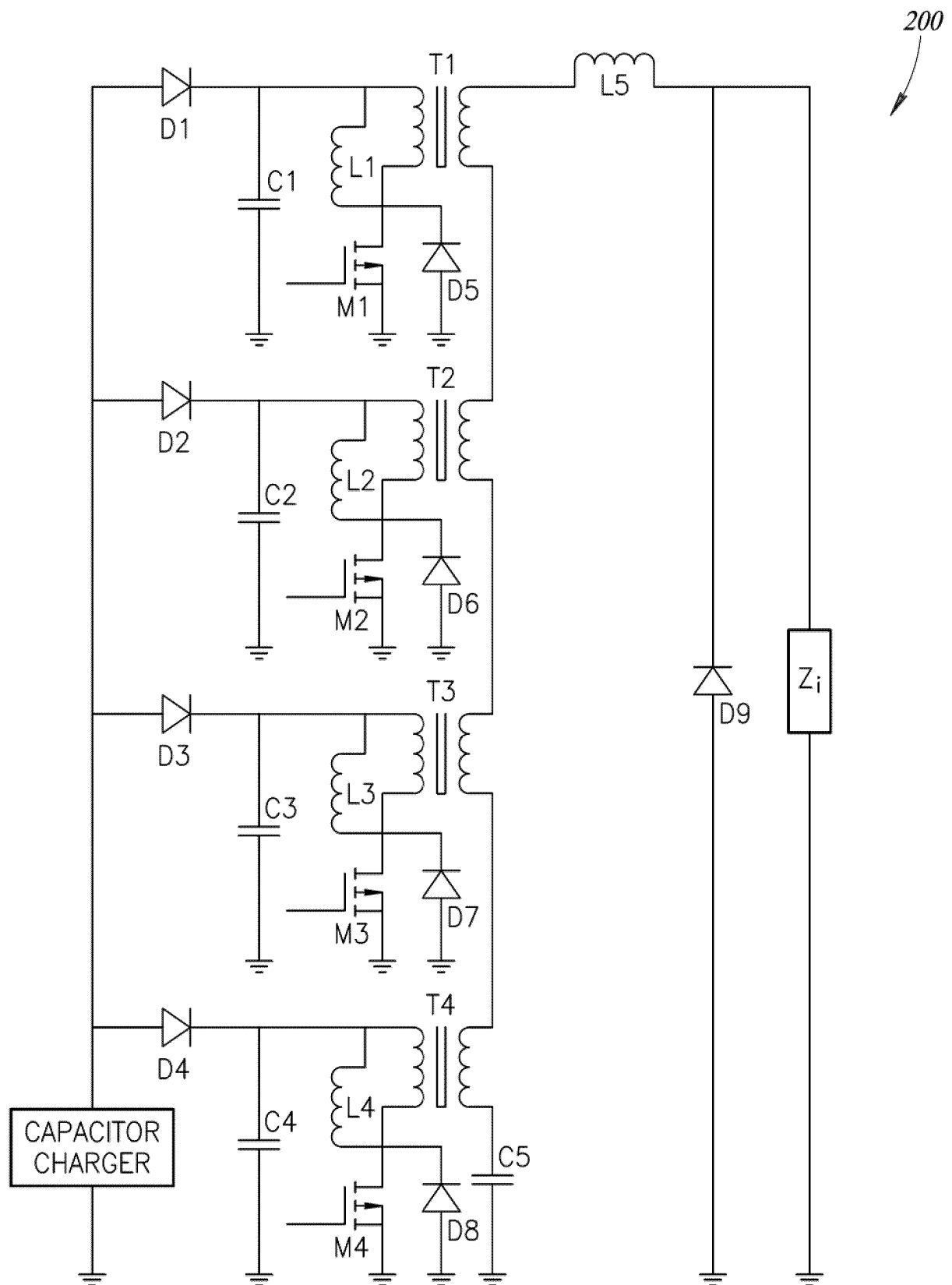


FIG. 2

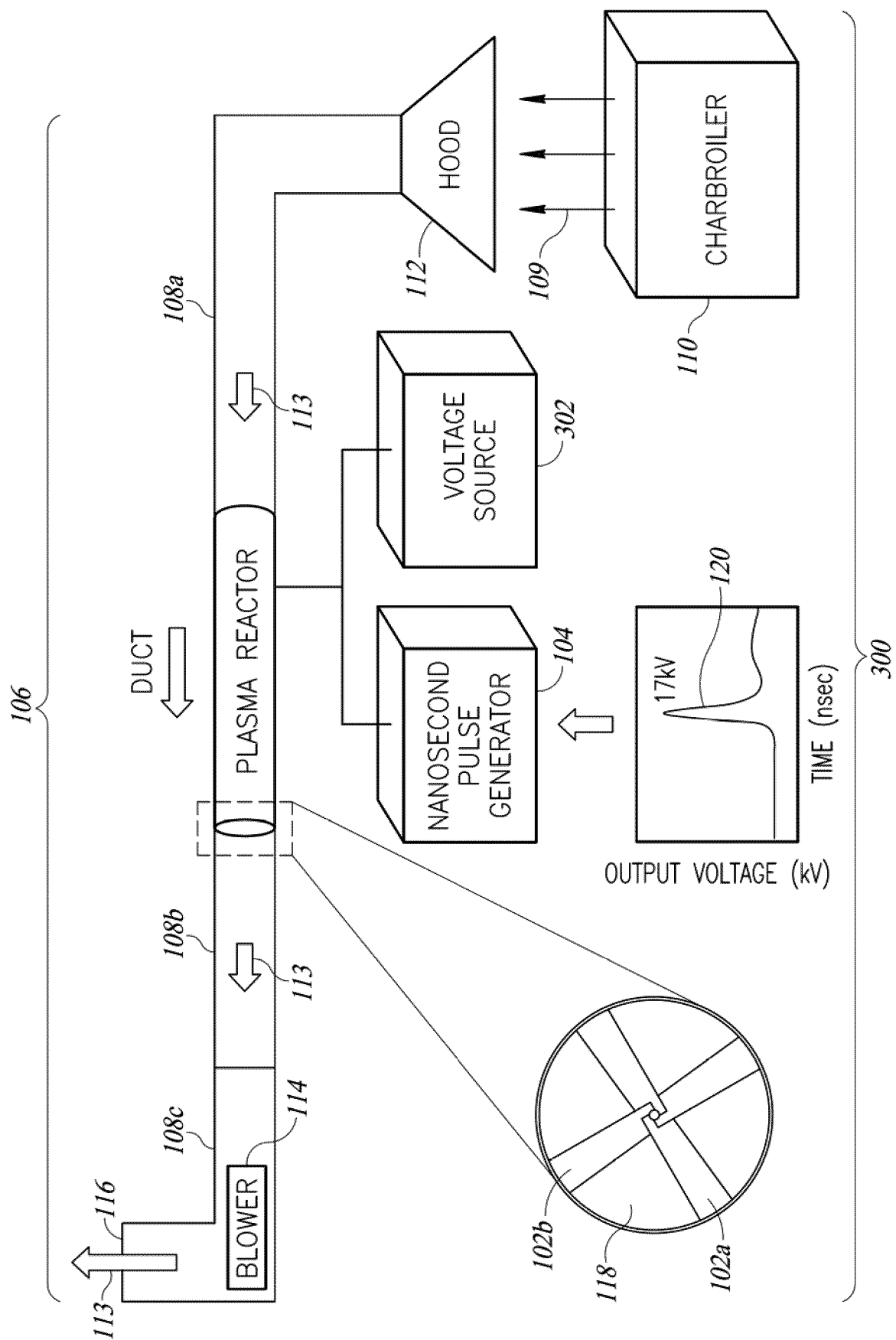


FIG. 3

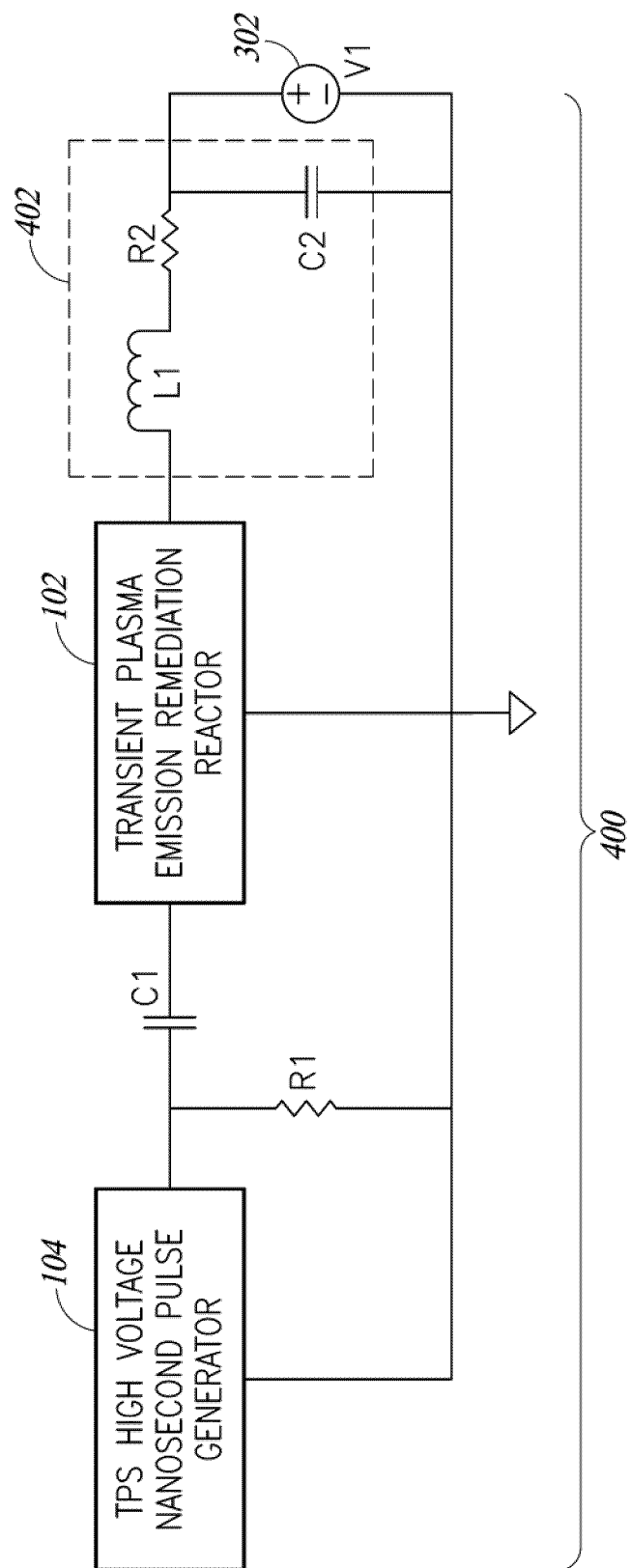


FIG. 4

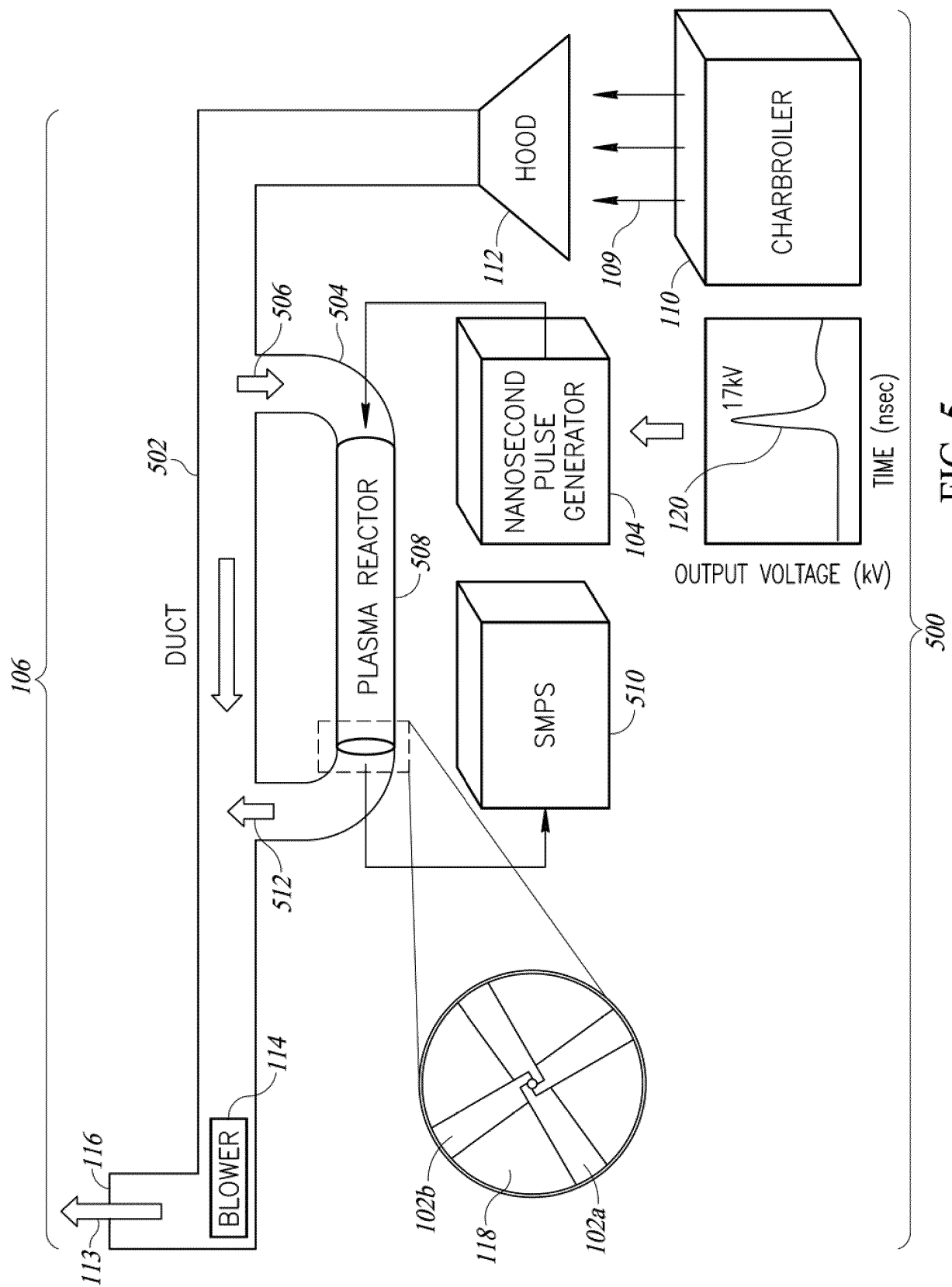


FIG. 5

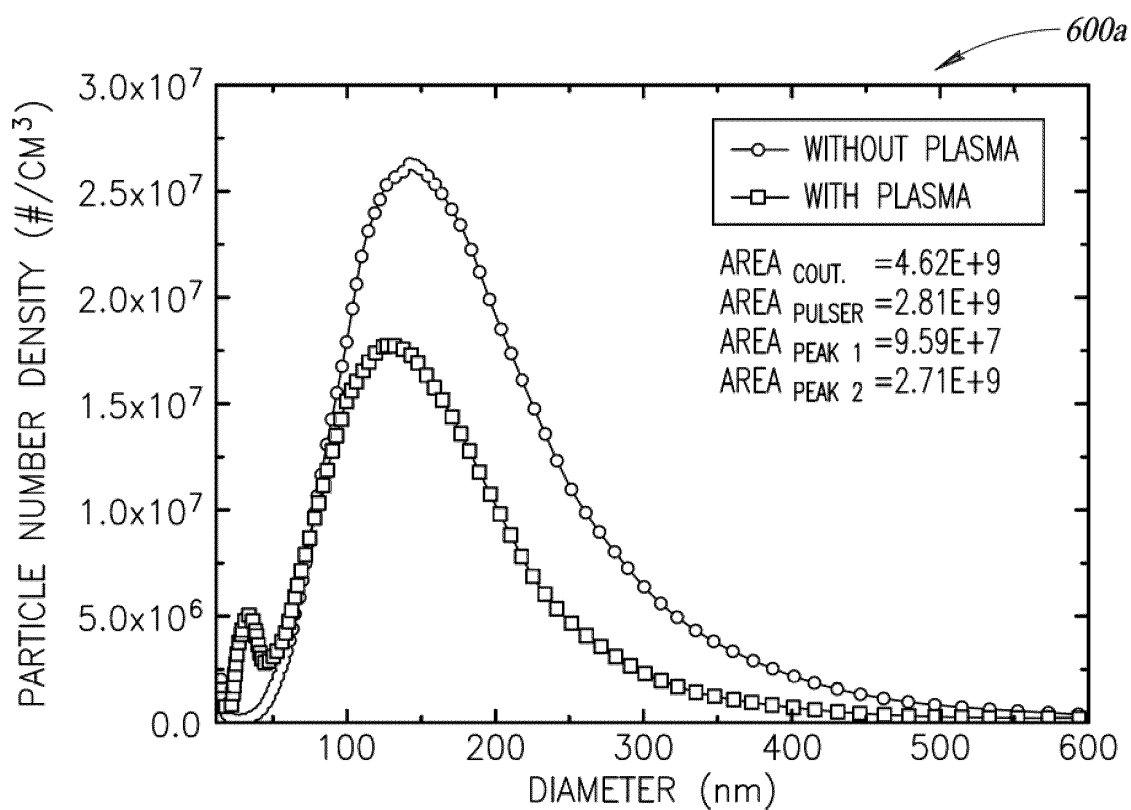


FIG. 6A

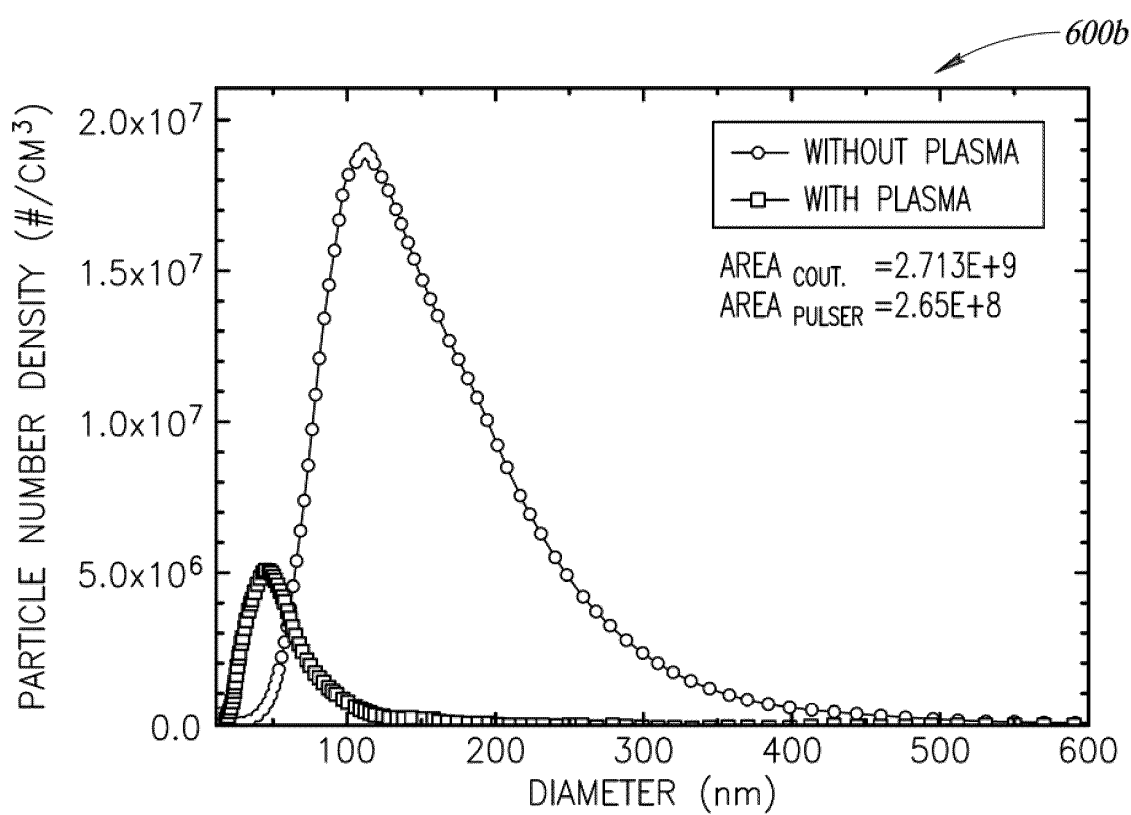


FIG. 6B

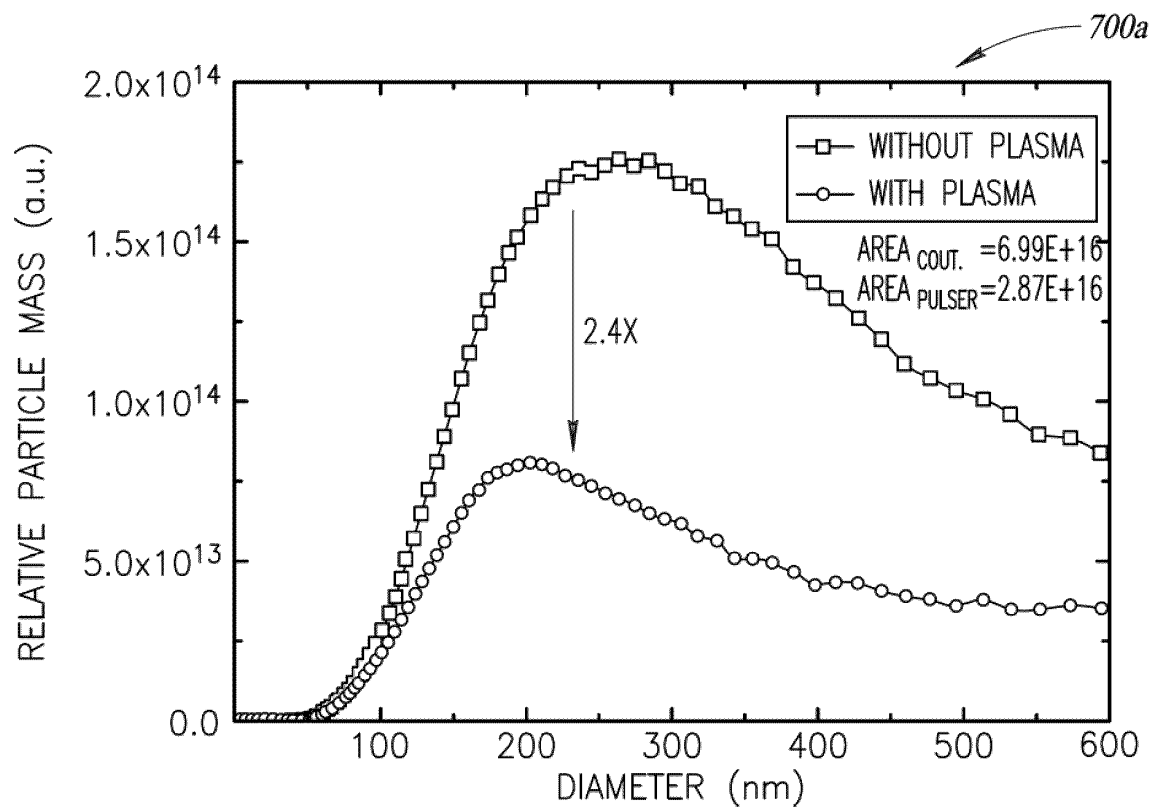


FIG. 7A

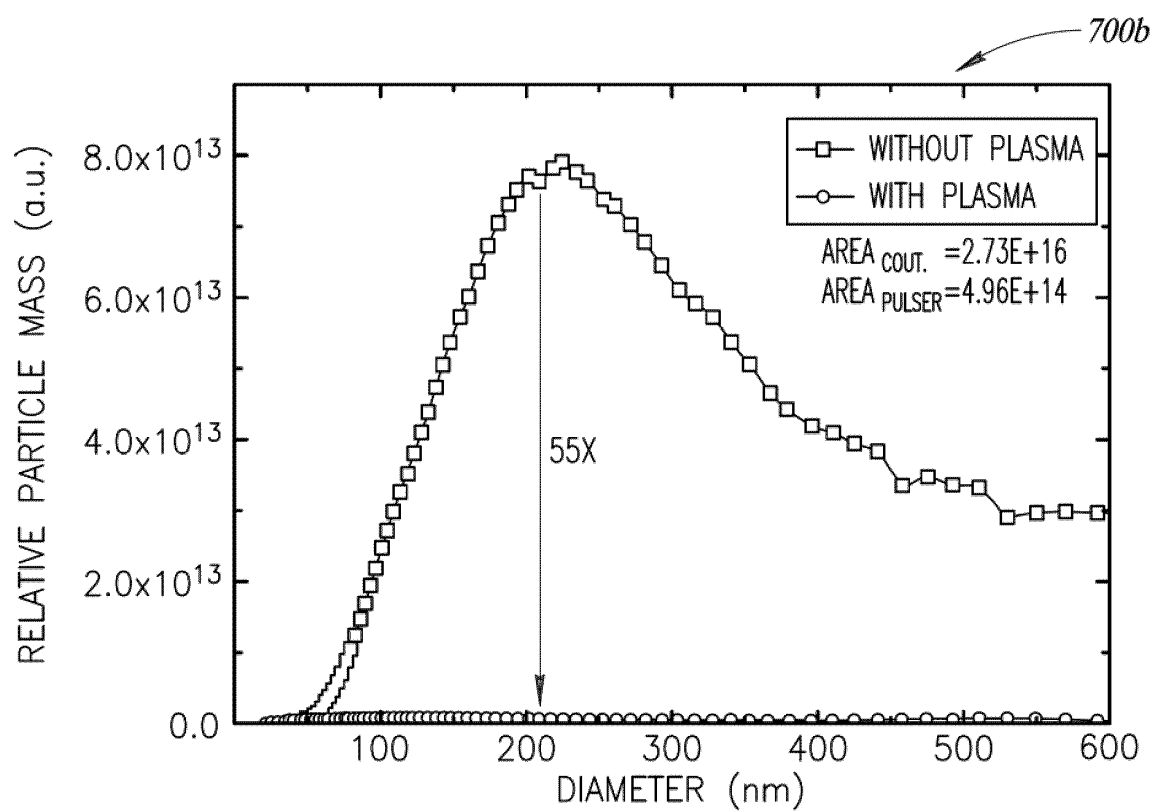


FIG. 7B

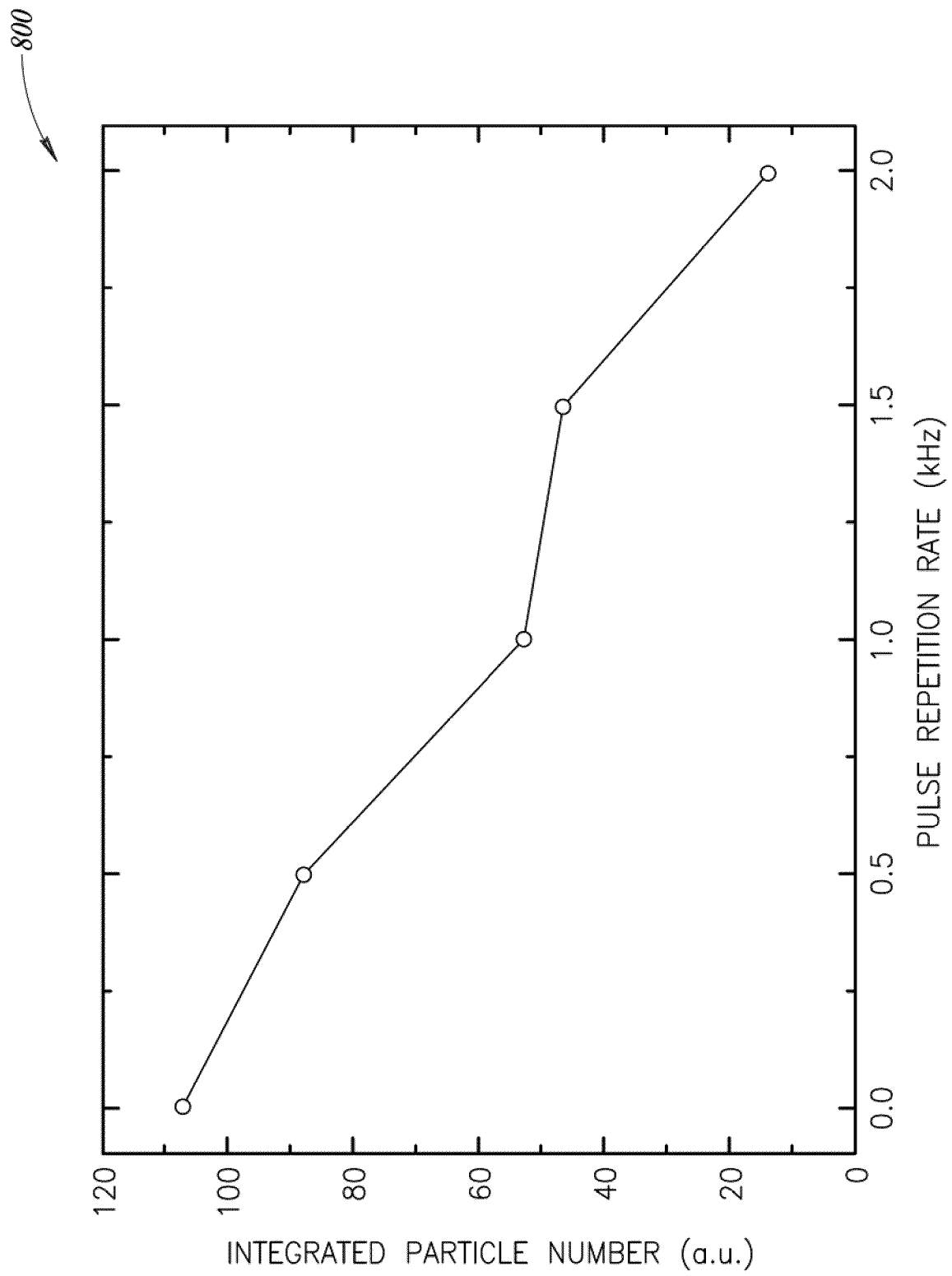


FIG. 8

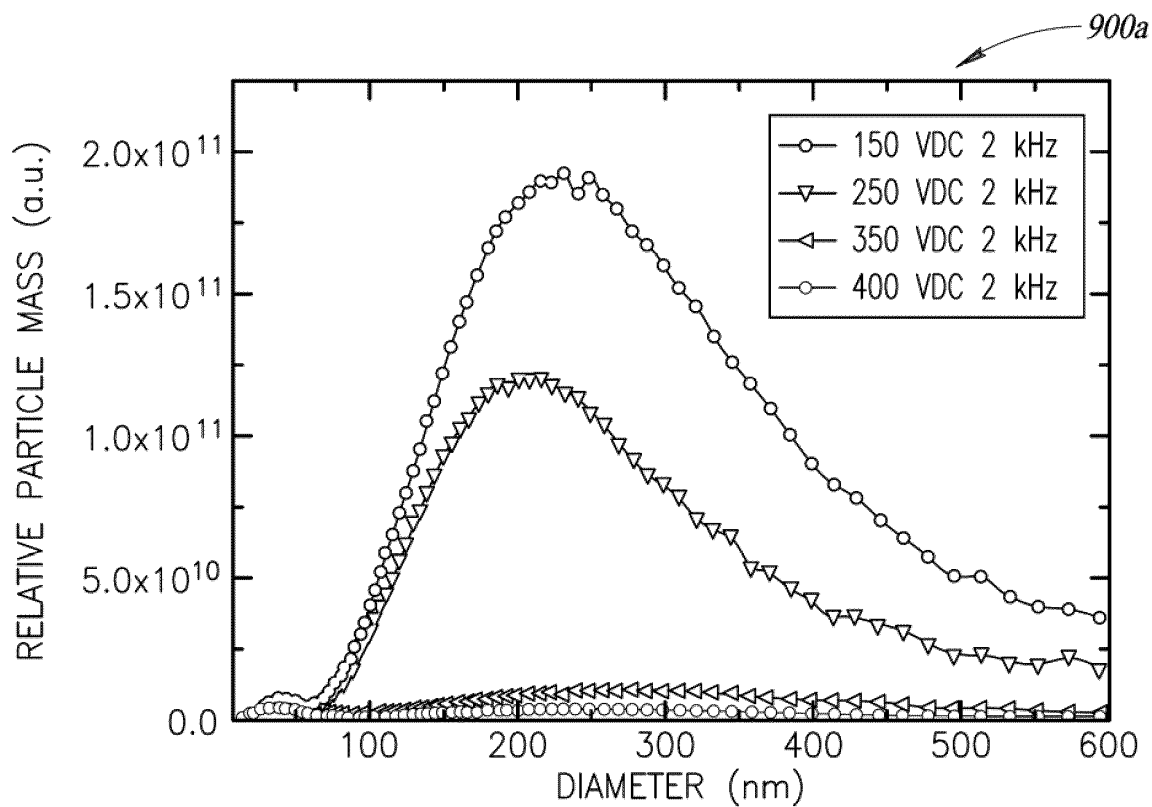


FIG. 9A

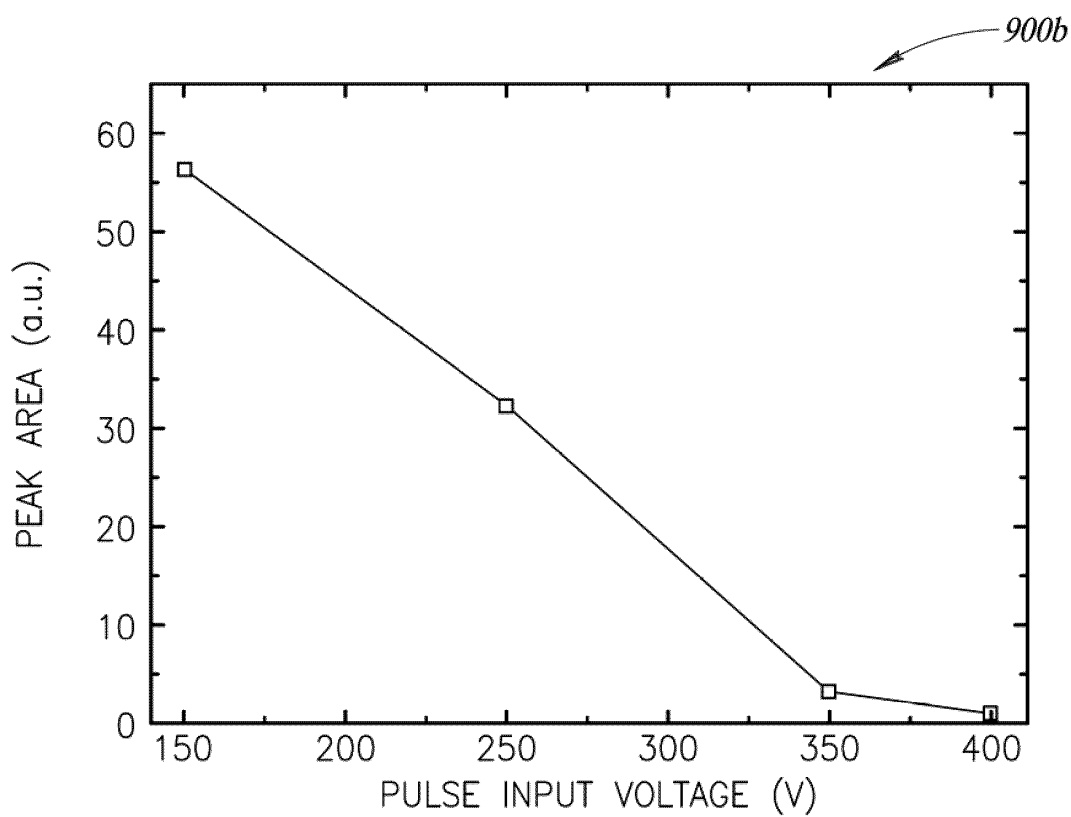


FIG. 9B

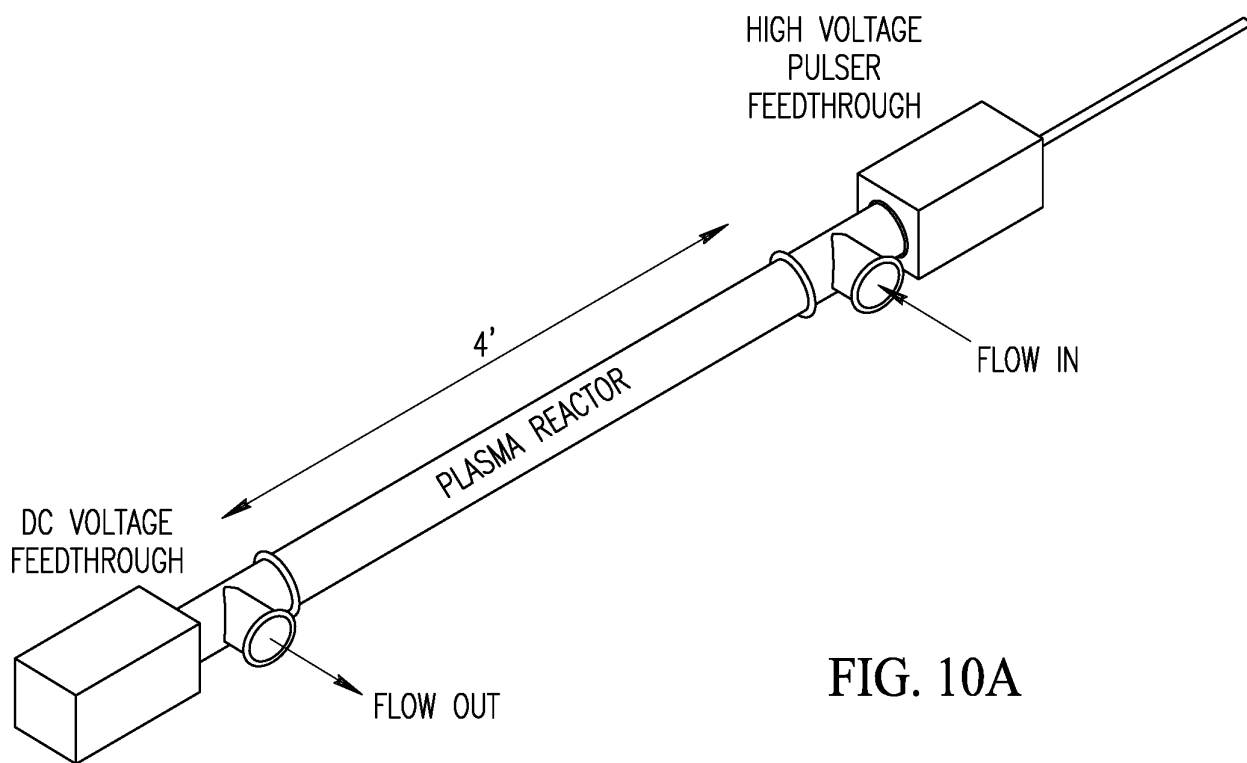


FIG. 10A

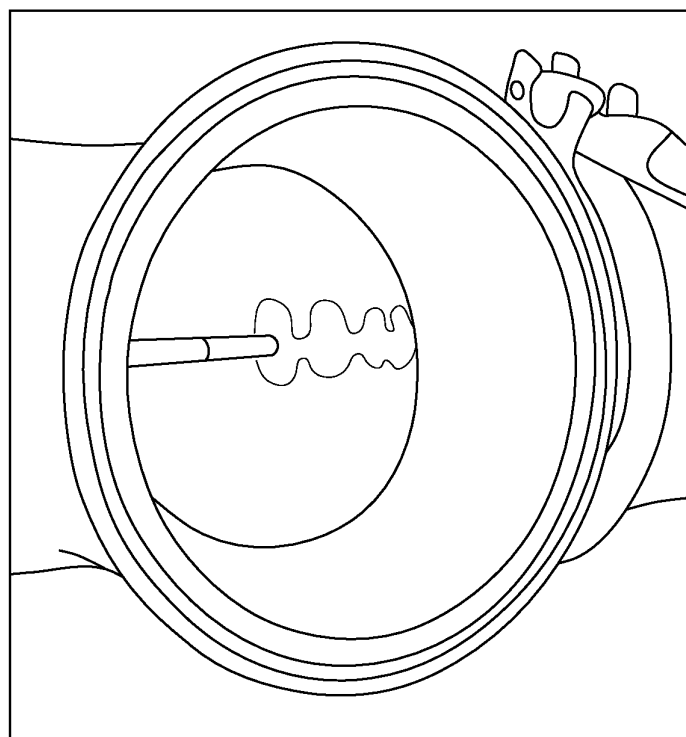


FIG. 10B

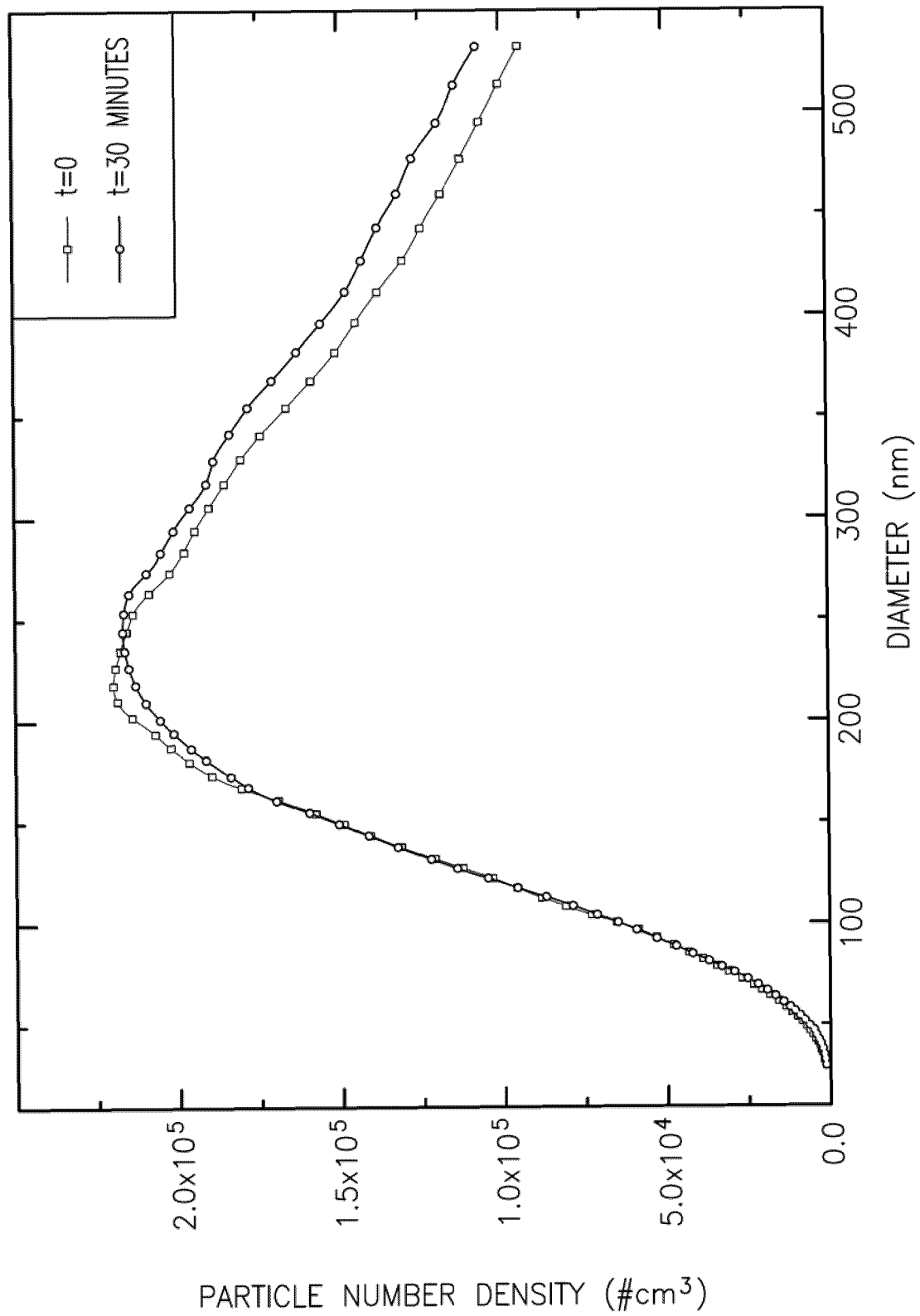


FIG. 11

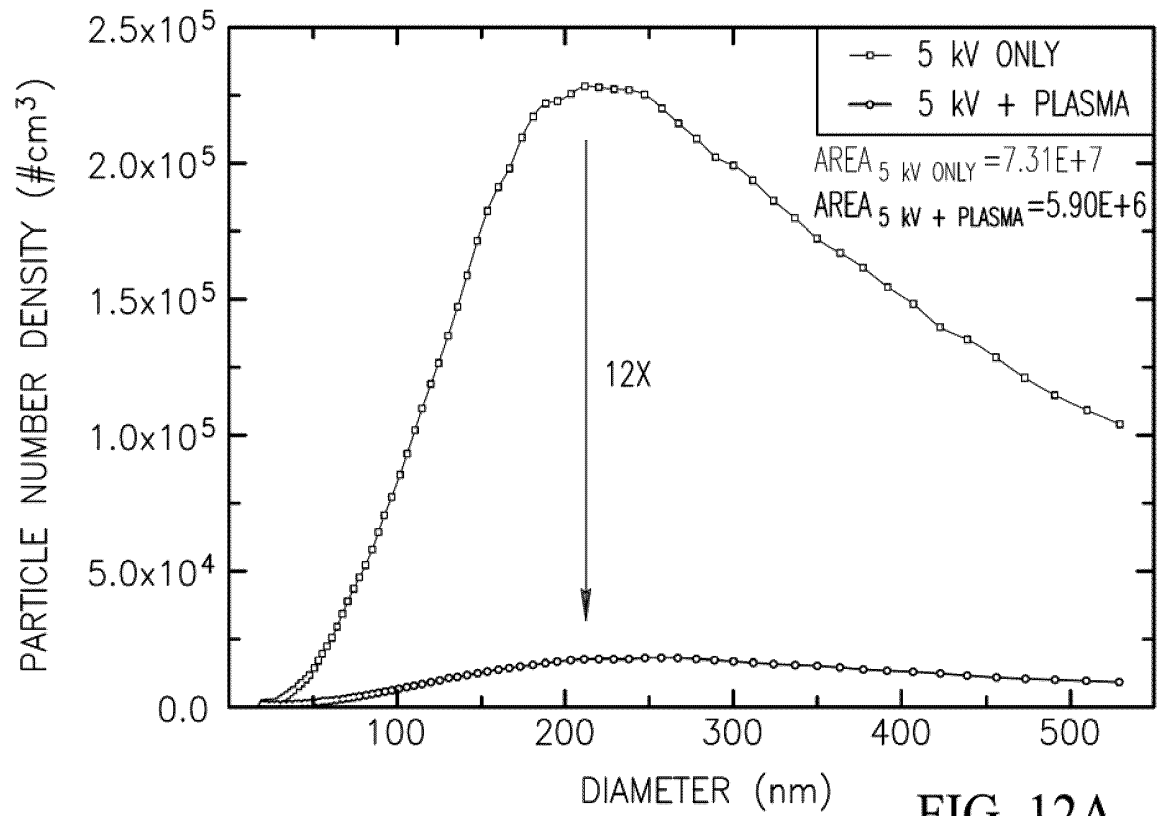


FIG. 12A

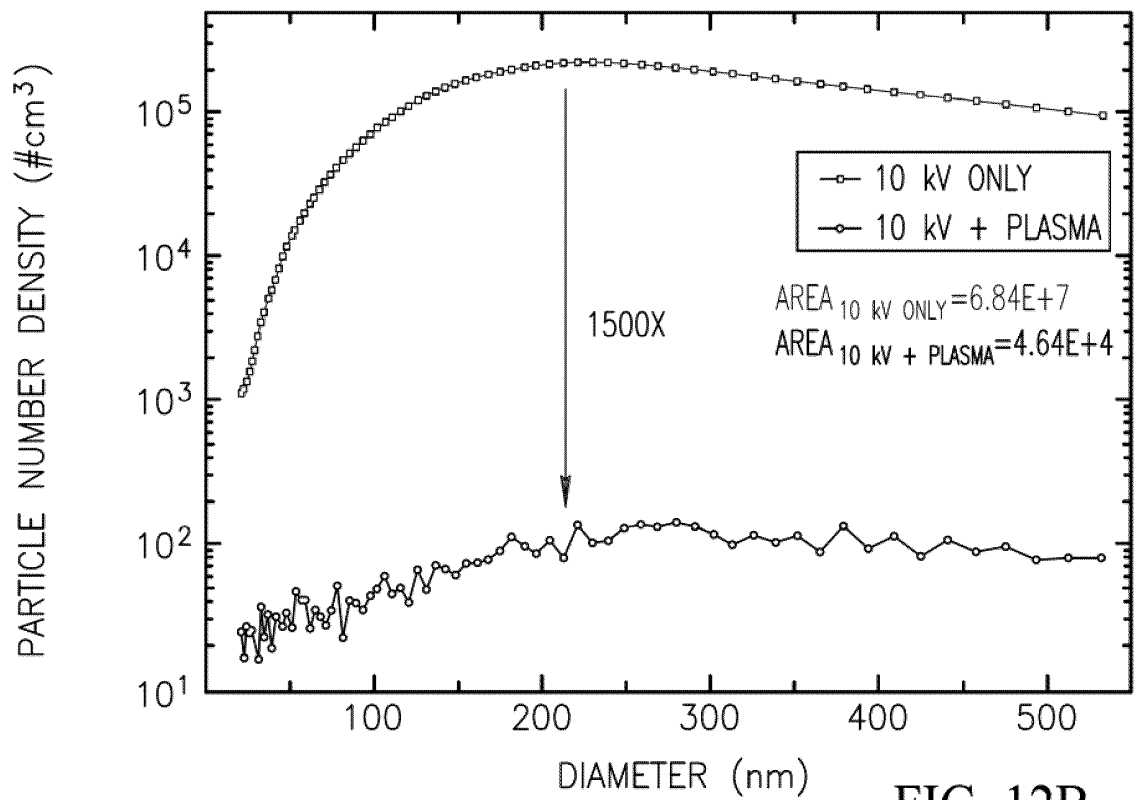


FIG. 12B

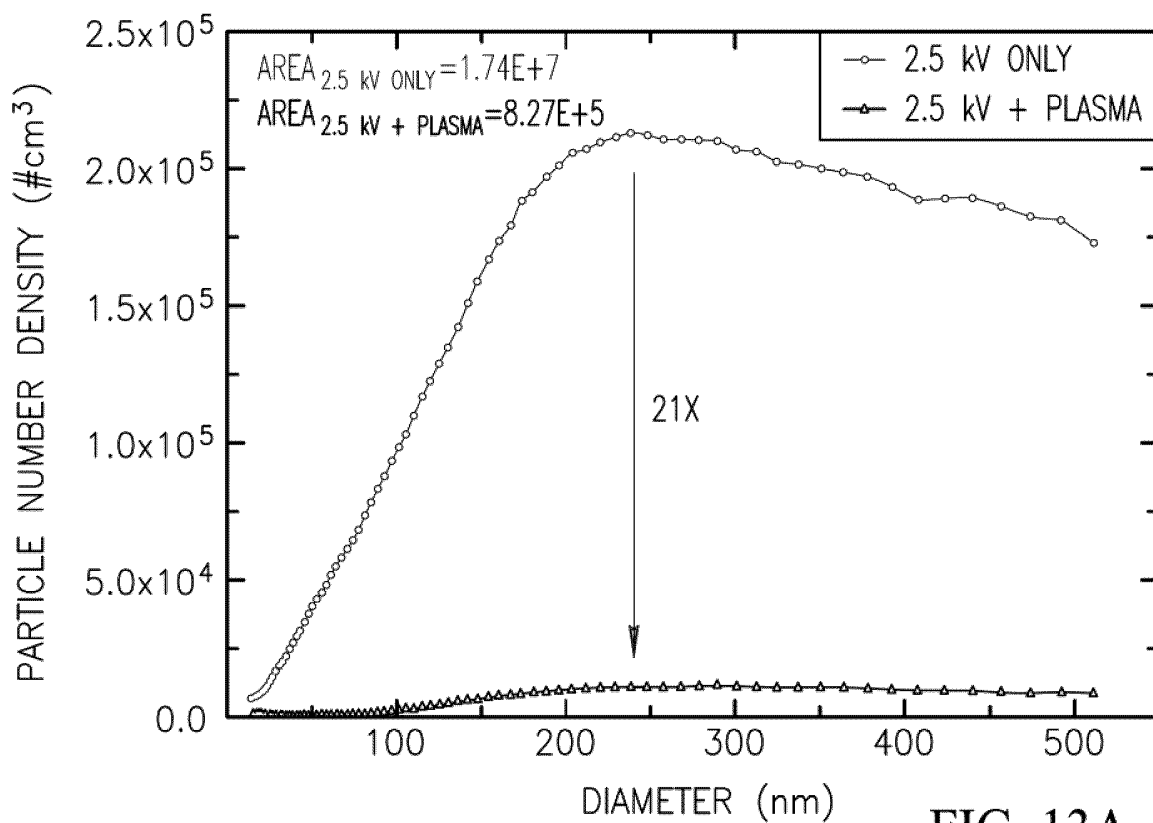


FIG. 13A

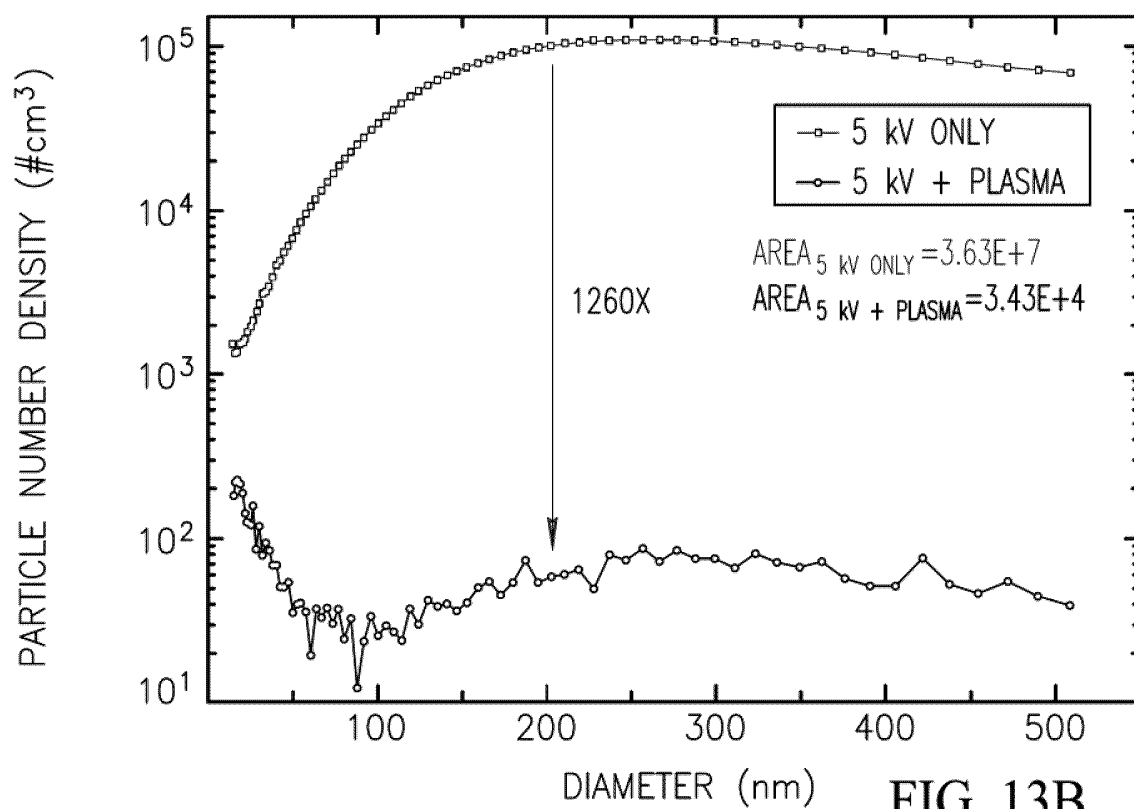


FIG. 13B



EUROPEAN SEARCH REPORT

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The present search report has been drawn up for all claims			
Place of search Munich		Date of completion of the search 4 December 2020	Examiner Harf, Julien
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The present search report has been drawn up for all claims			TECHNICAL FIELDS SEARCHED (IPC)
Place of search Munich		Date of completion of the search 4 December 2020	Examiner Harf, Julien
CATEGORY OF CITED DOCUMENTS X : particularly relevant if taken alone Y : particularly relevant if combined with another document of the same category A : technological background O : non-written disclosure P : intermediate document T : theory or principle underlying the invention E : earlier patent document, but published on, or after the filing date D : document cited in the application L : document cited for other reasons & : member of the same patent family, corresponding document			

1 EPO FORM 1503 03.82 (P04C01)

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